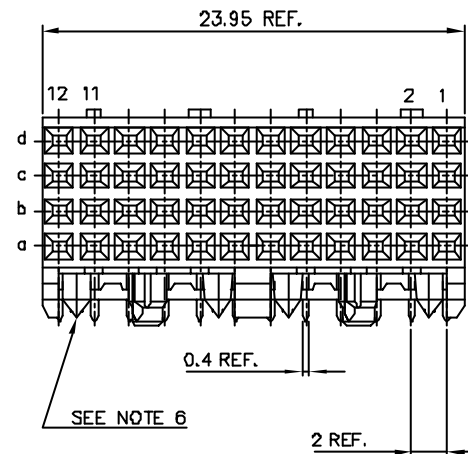
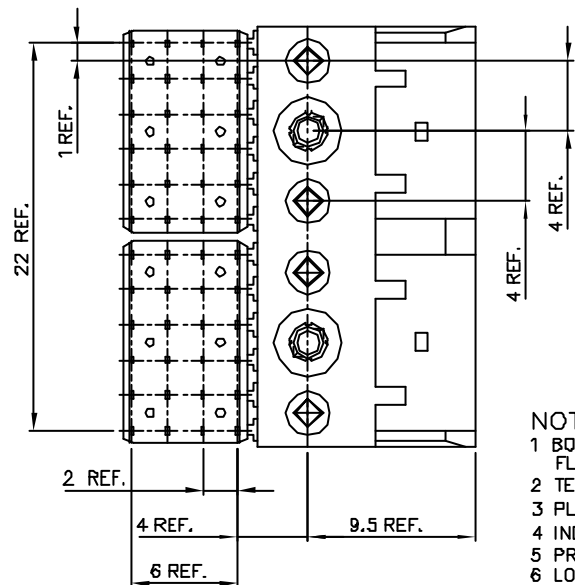
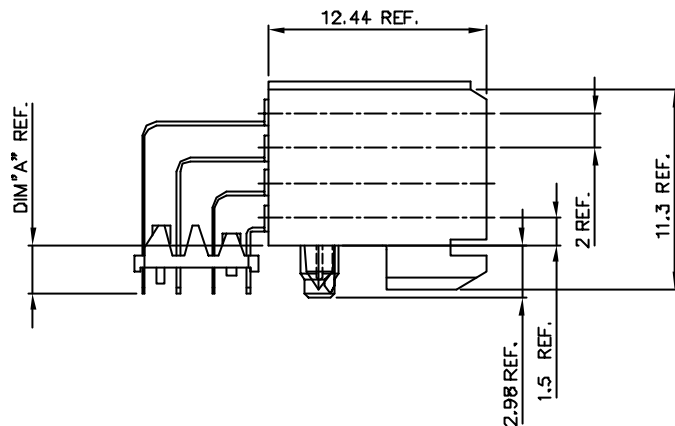
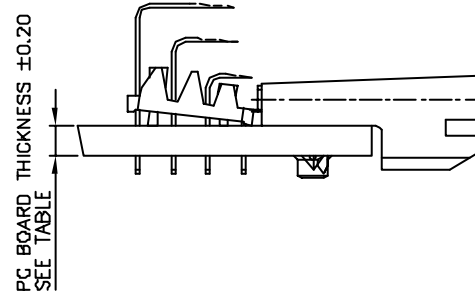


PC BOARD VERSIONS		
PRODUCTNR.	PCB THICKNESS	DIM "A"
89036-X01/X01LF	1.6	2.73
89036-X11/X11LF	2.4	3.53



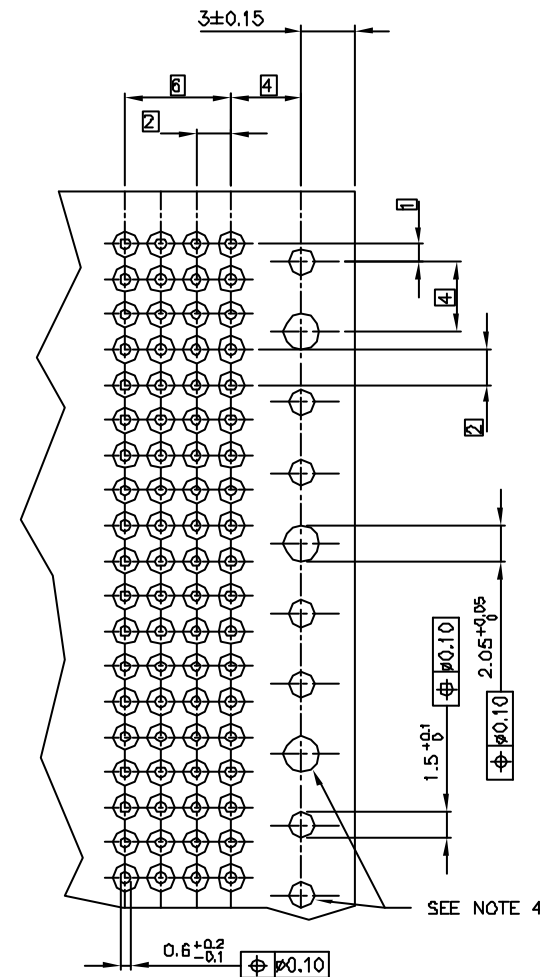
PRODUCT AFTER PC BOARD APPLICATION.



PC BOARD THICKNESS ±0.20
SEE TABLE

NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 μm SnPb 90-97 OR 2-8 μm PURE Sn
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
- 6 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
- 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.



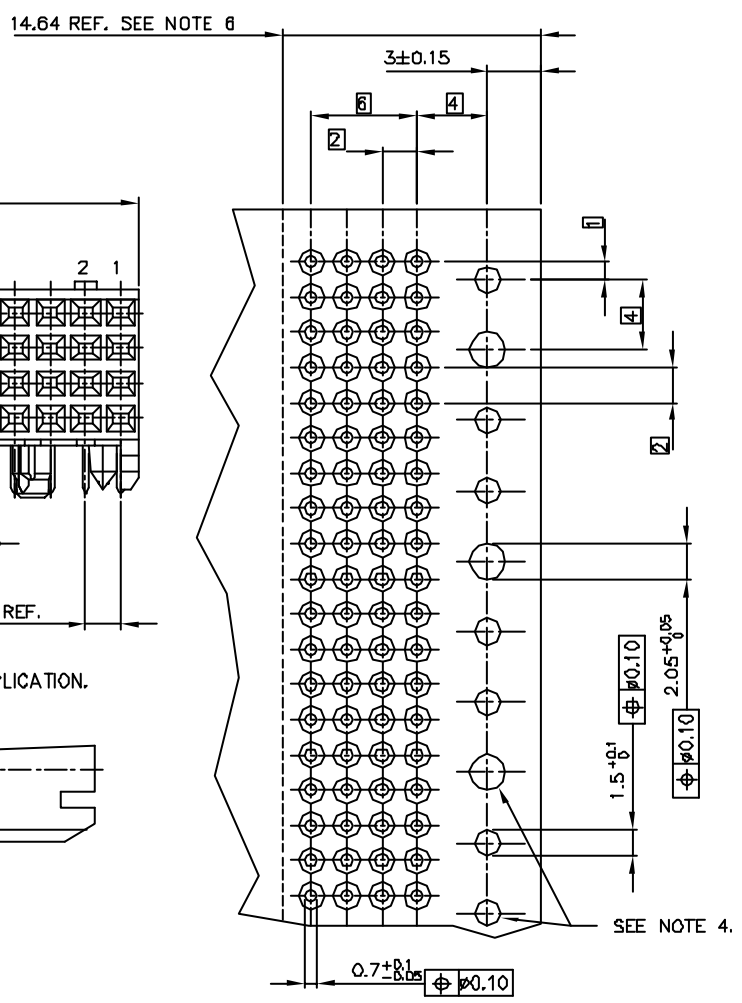
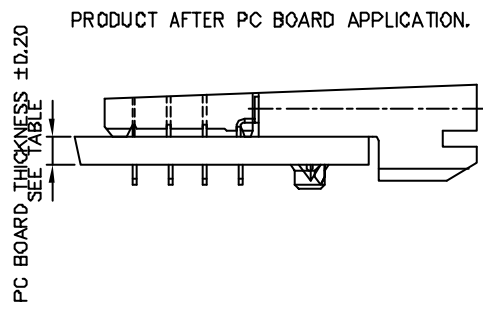
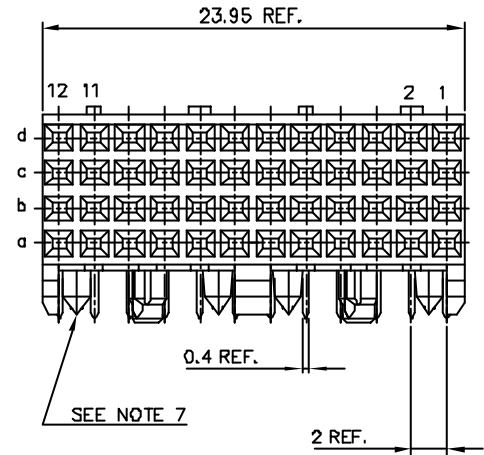
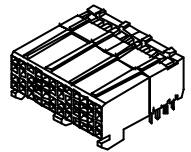
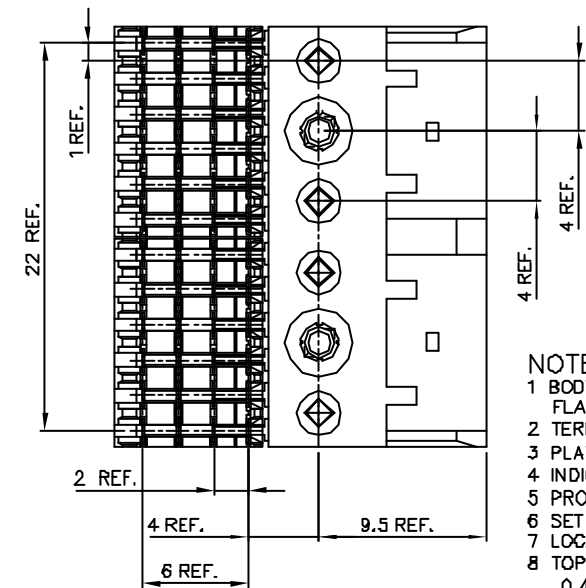
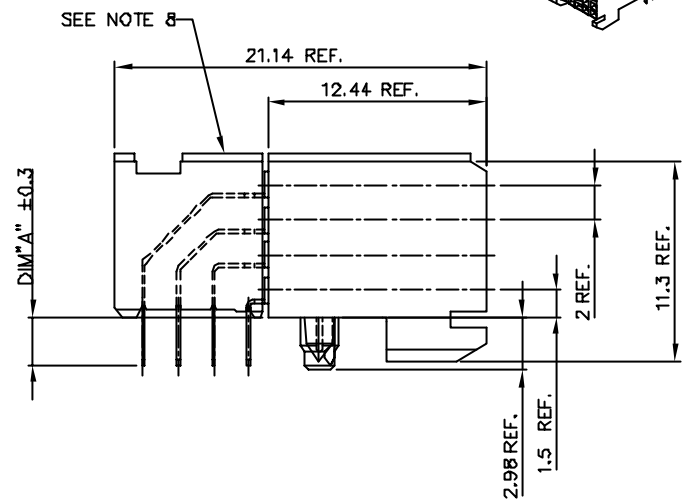
RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

PRODUCT NR.	PLATING CONTACT AREA	UNDERPLATING
89036-1YZ/1YZLF	0.8 μm GOLD	1.3 μm Ni MIN.
89036-2YZ/2YZLF	2 μm GOLD	1.3 μm Ni MIN.
89036-3YZ/3YZLF	1.3 μm GOLD	1.3 μm Ni MIN.
89036-9YZ/9YZLF	0.8 μm GXT	1.3 μm Ni MIN.

mat'l code				tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	ean no	dr	date	linear	angles	projection	title	product form	code
J	8904-0104	CU	041221						
D	H40366	008	040027	linear	angles	projection	title	product form	code
F	V70767	008	070530						
F	V81480	008	090827	linear	angles	projection	title	product form	code
G	V00078	008	000318						
H	V00047	008	000530	linear	angles	projection	title	product form	code
I	V00047	008	000530						
sheet	revision	J	J	linear	angles	projection	title	product form	code
index	sheet	1	2						

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PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM "A"
89036-X02/X02LF	1.6	2.73
89036-X12/X12LF	2.4	3.53



- NOTES:**
- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
 - 4 INDICATED HOLES ARE UNPLATED.
 - 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
 - 6 SET BACK FOR PRESS BLOCK.
 - 7 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
 - 8 TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD
 - 9 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 - 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA	UNDERPLATING
89036-1YZ/1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
89036-2YZ/2YZLF	2 µm GOLD	1.3 µm Ni MIN.
89036-3YZ/3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
89036-9YZ/9YZLF	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		F41 ELECTRONICS	
itr	ean no	dr	date	linear	projection	title	RA FEMALE SIGNAL
j						24 mm PRESS PEC	
				angles		product form	213
				dr	0.45 mm	size	2 of
				eng	P. Scholt	dwg no	
				chr	P. Scholt	scale	
				appl	0.45 mm	8:1	
sheet	revision						
index	sheet						